Features

- Fast Read Access Time 120 ns
- Automatic Page Write Operation
 - Internal Address and Data Latches for 128 Bytes
 - Internal Control Timer
- Fast Write Cycle Time
 - Page Write Cycle Time 10 ms Maximum
 - 1 to 128-byte Page Write Operation
- Low Power Dissipation
 - 40 mA Active Current
 - 200 µA CMOS Standby Current
- Hardware and Software Data Protection
- DATA Polling for End of Write Detection
- High Reliability CMOS Technology
 - Endurance: 10⁴ or 10⁵ Cycles
 - Data Retention: 10 Years
- Single 5V ± 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- JEDEC Approved Byte-wide Pinout
- Industrial Temperature Ranges
- Green (Pb/Halide-free) Packaging Option Only

1. Description

The AT28C010 is a high-performance electrically-erasable and programmable read-only memory. Its 1 megabit of memory is organized as 131,072 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 120 ns with power dissipation of just 220 mW. When the device is deselected, the CMOS standby current is less than 200 μ A.

The AT28C010 is accessed like a Static RAM for the read or write cycle without the need for external components. The device contains a 128-byte page register to allow writing of up to 128 bytes simultaneously. During a write cycle, the address and 1 to 128 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a write cycle, the device will automatically write the latched data using an internal control timer. The end of a write cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a write cycle has been detected a new access for a read or write can begin.

Atmel's AT28C010 has additional features to ensure high quality and manufacturability. The device utilizes internal error correction for extended endurance and improved data retention characteristics. An optional software data protection mechanism is available to guard against inadvertent writes. The device also includes an extra 128 bytes of EEPROM for device identification or tracking.



1-megabit (128K x 8) Paged Parallel EEPROM

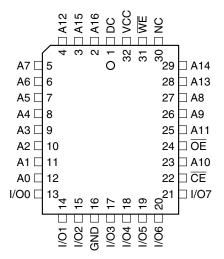
AT28C010



2. Pin Configurations

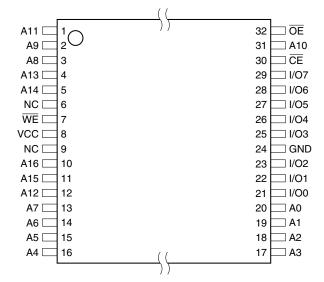
Pin Name	Function
A0 - A16	Addresses
CE	Chip Enable
ŌĒ	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect
DC	Don't Connect

2.2 32-lead PLCC Top View

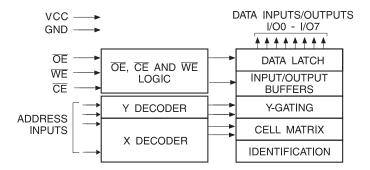


Note: PLCC package pin 1 is Don't Connect.

2.1 32-lead TSOP Top View



3. Block Diagram



4. Device Operation

4.1 Read

The AT28C010 is accessed like a Static RAM. When \overline{CE} and \overline{OE} are low and \overline{WE} is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state when either \overline{CE} or \overline{OE} is high. This dual-line control gives designers flexibility in preventing bus contention in their system.

4.2 Byte Write

A low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high initiates a write cycle. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$. Once a byte write has been started it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of t_{WC} , a read operation will effectively be a polling operation.

4.3 Page Write

The page write operation of the AT28C010 allows 1 to 128 bytes of data to be written into the device during a single internal programming period. A page write operation is initiated in the same manner as a byte write; the first byte written can then be followed by 1 to 127 additional bytes. Each successive byte must be written within 150 μ s (t_{BLC}) of the previous byte. If the t_{BLC} limit is exceeded the AT28C010 will cease accepting data and commence the internal programming operation. All bytes during a page write operation must reside on the same page as defined by the state of the A7 - A16 inputs. For each \overline{WE} high to low transition during the page write operation, A7 - A16 must be the same.

The A0 to A6 inputs are used to specify which bytes within the page are to be written. The bytes may be loaded in any order and may be altered within the same load period. Only bytes which are specified for writing will be written; unnecessary cycling of other bytes within the page does not occur.

4.4 DATA Polling

The AT28C010 features DATA Polling to indicate the end of a write cycle. During a byte or page write cycle an attempted read of the last byte written will result in the complement of the written data to be presented on I/O₇. Once the write cycle has been completed, true data is valid on all outputs, and the next write cycle may begin. DATA Polling may begin at anytime during the write cycle.





4.5 Toggle Bit

In addition to DATA Polling the AT28C010 provides another method for determining the end of a write cycle. During the write operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the write has completed, I/O6 will stop toggling and valid data will be read. Reading the toggle bit may begin at any time during the write cycle.

4.6 Data Protection

If precautions are not taken, inadvertent writes may occur during transitions of the host system power supply. Atmel® has incorporated both hardware and software features that will protect the memory against inadvertent writes.

4.6.1 Hardware Protection

Hardware features protect against inadvertent writes to the AT28C010 in the following ways: (a) V_{CC} sense – if V_{CC} is below 3.8V (typical) the write function is inhibited; (b) V_{CC} power-on delay – once V_{CC} has reached 3.8V the device will automatically time out 5 ms (typical) before allowing a write; (c) write inhibit – holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits write cycles; and (d) noise filter—pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a write cycle.

4.6.2 Software Data Protection

A software controlled data protection feature has been implemented on the AT28C010. When enabled, the software data protection (SDP), will prevent inadvertent writes. The SDP feature may be enabled or disabled by the user; the AT28C010 is shipped from Atmel with SDP disabled.

SDP is enabled by the host system issuing a series of three write commands; three specific bytes of data are written to three specific addresses (refer to Software Data Protection Algorithm). After writing the 3-byte command sequence and after t_{WC} the entire AT28C010 will be protected against inadvertent write operations. It should be noted, that once protected the host may still perform a byte or page write to the AT28C010. This is done by preceding the data to be written by the same 3-byte command sequence used to enable SDP.

Once set, SDP will remain active unless the disable command sequence is issued. Power transitions do not disable SDP and SDP will protect the AT28C010 during power-up and power-down conditions. All command sequences must conform to the page write timing specifications. The data in the enable and disable command sequences is not written to the device and the memory addresses used in the sequence may be written with data in either a byte or page write operation.

After setting SDP, any attempt to write to the device without the 3-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{WC} , read operations will effectively be polling operations.

4.7 Device Identification

An extra 128 bytes of EEPROM memory are available to the user for device identification. By raising A9 to $12V \pm 0.5V$ and using address locations 1FF80H to 1FFFFH the bytes may be written to or read from in the same manner as the regular memory array.

4.8 Optional Chip Erase Mode

The entire device can be erased using a 6-byte software code. Please see Software Chip Erase application note for details.

4 AT28C010

5. DC and AC Operating Range

		AT28C010-12	AT28C010-15
Operating Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply	•	5V ±10%	5V ±10%

6. Operating Modes

Mode	CE	ŌĒ	WE	I/O
Read	V _{IL}	V _{IL}	V _{IH}	D _{OUT}
Write ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	D _{IN}
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	Х	High Z
Write Inhibit	X	X	V _{IH}	
Write Inhibit	X	V _{IL}	X	
Output Disable	X	V _{IH}	X	High Z

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to AC Programming Waveforms.

7. Absolute Maximum Ratings*

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V
All Output Voltages with Respect to Ground0.6V to V _{CC} + 0.6V
Voltage on $\overline{\text{OE}}$ and A9 with Respect to Ground0.6V to +13.5V

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

8. DC Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	$V_{IN} = 0V$ to $V_{CC} + 1V$		10	μΑ
I _{LO}	Output Leakage Current	$V_{I/O} = 0V \text{ to } V_{CC}$		10	μΑ
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{\text{CE}} = \text{V}_{\text{CC}} - 0.3 \text{V to V}_{\text{CC}} + 1 \text{V}$		200	μΑ
I _{SB2}	V _{CC} Standby Current TTL	$\overline{\text{CE}}$ = 2.0V to V _{CC} + 1V		3	mA
I _{cc}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		40	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	$I_{OH} = -100 \mu A; V_{CC} = 4.5 V$	4.2		V

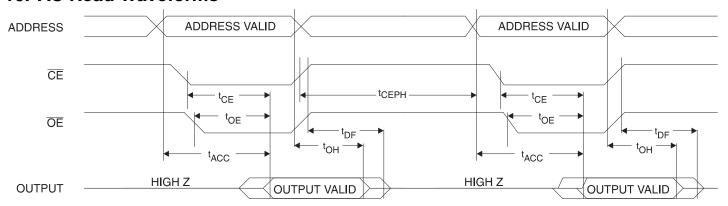




AC Read Characteristics

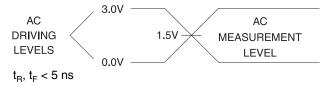
		AT28C010-12		AT28C010-15		
Symbol	Parameter	Min	Max	Min	Max	Units
t _{ACC}	Address to Output Delay		120		150	ns
t _{CE} ⁽¹⁾	CE to Output Delay		120		150	ns
t _{OE} ⁽²⁾	OE to Output Delay	0	50	0	55	ns
t _{DF} ⁽³⁾⁽⁴⁾	CE or OE to Output Float	0	50	0	55	ns
t _{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, Whichever Occurred First	0		0		ns
t _{CEPH} ⁽⁵⁾	CE Pulse High Time	50		50		ns

10. AC Read Waveforms⁽¹⁾⁽²⁾⁽³⁾⁽⁴⁾

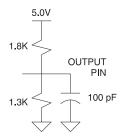


- Notes: 1. \overline{CE} may be delayed up to t_{ACC} t_{CE} after the address transition without impact on t_{ACC} .
 - 2. $\overline{\text{OE}}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} or by t_{ACC} t_{OE} after an address change without impact on t_{ACC} .
 - 3. t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5 \text{ pF}$).
 - 4. This parameter is characterized and is not 100% tested.
 - 5. If CE is de-asserted, it must remain de-asserted for at least 50ns during read operations otherwise incorrect data may be read.

11. Input Test Waveforms and Measurement Level



12. Output Test Load



13. Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ}C^{(1)}$

Symbol	Тур	Max	Units	Conditions
C _{IN}	4	10	pF	$V_{IN} = 0V$
C _{OUT}	8	12	pF	V _{OUT} = 0V

Note: 1. This parameter is characterized and is not 100% tested.



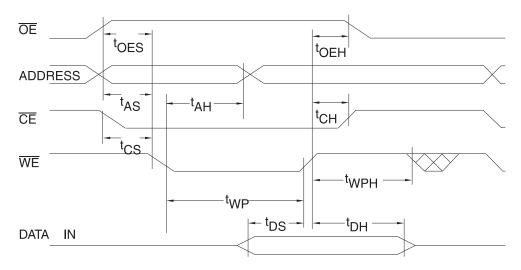


14. AC Write Characteristics

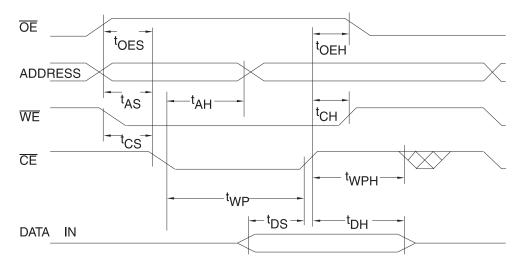
Symbol	Parameter	Min	Max	Units
t _{AS} , t _{OES}	Address, OE Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{CS}	Chip Select Set-up Time	0		ns
t _{CH}	Chip Select Hold Time	0		ns
t _{WP}	Write Pulse Width (WE or CE)	100		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH} , t _{OEH}	Data, OE Hold Time	0		ns

15. AC Write Waveforms

15.1 WE Controlled



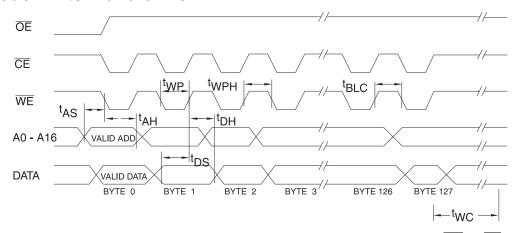
15.2 **CE** Controlled



16. Page Mode Characteristics

Symbol	Parameter	Min	Max	Units	
t _{WC}	Write Cycle Time		10	ms	
t _{AS}	Address Set-up Time	0		ns	
t _{AH}	Address Hold Time 50				
t _{DS}	Data Set-up Time	50		ns	
t _{DH}	Data Hold Time	0		ns	
t _{WP}	Write Pulse Width	100		ns	
t _{BLC}	Byte Load Cycle Time		150	μs	
t _{WPH}	Write Pulse Width High	50		ns	

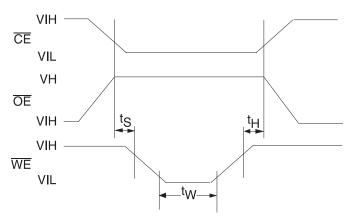
17. Page Mode Write Waveforms⁽¹⁾⁽²⁾



Notes: 1. A7 through A16 must specify the same page address during each high to low transition of WE (or CE).

2. $\overline{\text{OE}}$ must be high only when $\overline{\text{WE}}$ and $\overline{\text{CE}}$ are both low.

18. Chip Erase Waveforms

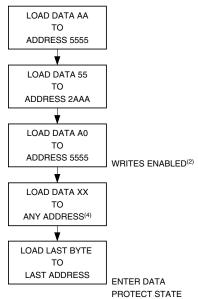


$$\begin{split} t_{S} &= 5 \; \mu sec \; (min.) \\ t_{W} &= t_{H} = 10 \; msec \; (min.) \\ V_{H} &= 12.0V \; \pm 0.5V \end{split}$$



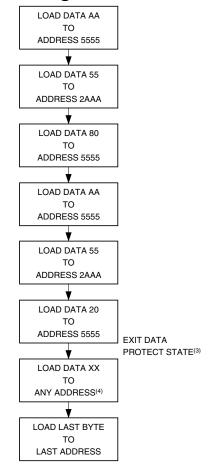


19. Software Data Protection **Enable Algorithm**⁽¹⁾

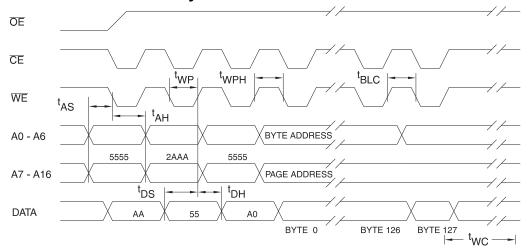


- Notes: 1. Data Format: I/O7 I/O0 (Hex); Address Format: A14 - A0 (Hex).
 - 2. Write Protect state will be activated at end of write even if no other data is loaded.
 - 3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
 - 4. 1 to 128 bytes of data are loaded.

20. Software Data Protection Disable Algorithm⁽¹⁾



21. Software Protected Write Cycle Waveforms⁽¹⁾⁽²⁾⁽³⁾



1. A0 through A14 must conform to the addressing sequence for the first 3 bytes as shown above. Notes:

- 2. After the command sequence has been issued and a page write operation follows, the page address inputs (A7 A16) must be the same for each high to low transition of \overline{WE} (or \overline{CE}).
- 3. \overline{OE} must be high only when \overline{WE} and \overline{CE} are both low.

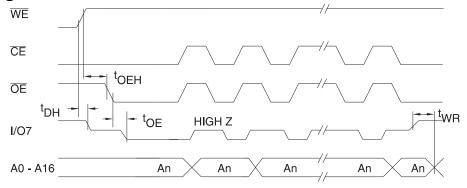
22. Data Polling Characteristics(1)

Symbol	Parameter	Min	Тур	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	OE Hold Time	10			ns
t _{OE}	OE to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

23. Data Polling Waveforms



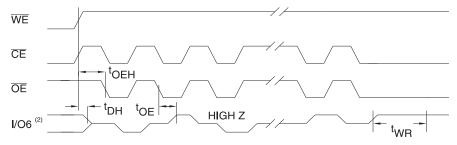
24. Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Тур	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	OE Hold Time	10			ns
t _{OE}	OE to Output Delay ⁽²⁾				ns
t _{OEHP}	OE High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

25. Toggle Bit Waveforms



Notes: 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.

- 2. Beginning and ending state of I/O6 will vary.
- 3. Any address location may be used but the address should not vary.





26. Ordering Information

26.1 Green Package Option (Pb/Halide-free)

26.1.1 AT28C010

t _{ACC}	I _{CC} (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
120	40	0.2	AT28C010-12JU	32J	
120	40	0.2	AT28C010-12TU	32T	Industrial
150	40	0.2	AT28C010-15JU	32J	(-40° to 85°C)
130	40	0.2	AT28C010-15TU	32T	

26.1.2 AT28C010E

t _{ACC} I _{CC} (mA)		(mA)			
(ns)	Active	Standby	Ordering Code	Package	Operation Range
120	40	0.2	AT28C010E-12JU	32J	
120 4	40		AT28C010E-12TU	32T	Industrial
150	150 40	40 0.2	AT28C010E-15JU	32J	(-40° to 85°C)
150			AT28C010E-15TU	32T	

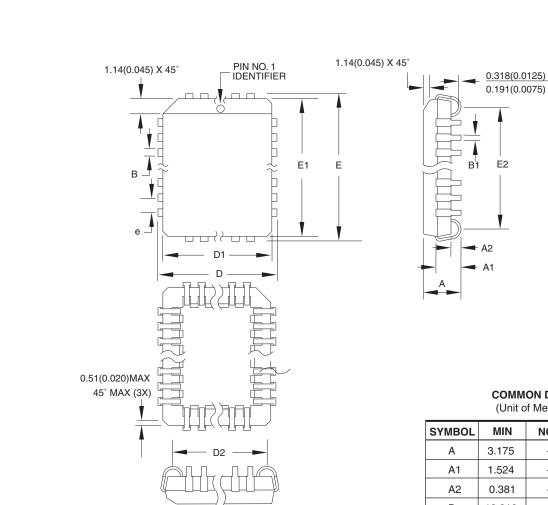
Package Type					
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)				
32T	32-lead, Plastic Thin Small Outline Package (TSOP)				
	Options				
Blank	Standard Device: Endurance = 10K Write Cycles; Write Time = 10 ms				
E	High-endurance Option: Endurance = 100K Write Cycles				

26.2 Die Products

Reference Section: Contact Atmel Sales for Parallel EEPROM Die Product availability.

27. Packaging Information

27.1 32J - PLCC



Notes:

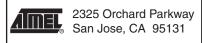
- 1. This package conforms to JEDEC reference MS-016, Variation AE.
- Dimensions D1 and E1 do not include mold protrusion.
 Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
- 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

COMMON DIMENSIONS

(Unit of Measure = mm)

MIN	NOM	MAX	NOTE
3.175	_	3.556	
1.524	-	2.413	
0.381	_	_	
12.319	_	12.573	
11.354	_	11.506	Note 2
9.906	_	10.922	
14.859	-	15.113	
13.894	_	14.046	Note 2
12.471	-	13.487	
0.660	_	0.813	
0.330	_	0.533	
	1.270 TYF)	
	3.175 1.524 0.381 12.319 11.354 9.906 14.859 13.894 12.471 0.660 0.330	3.175 - 1.524 - 0.381 - 12.319 - 11.354 - 9.906 - 14.859 - 13.894 - 12.471 - 0.660 - 0.330 -	3.175 - 3.556 1.524 - 2.413 0.381 - - 12.319 - 12.573 11.354 - 11.506 9.906 - 10.922 14.859 - 15.113 13.894 - 14.046 12.471 - 13.487 0.660 - 0.813

10/04/01



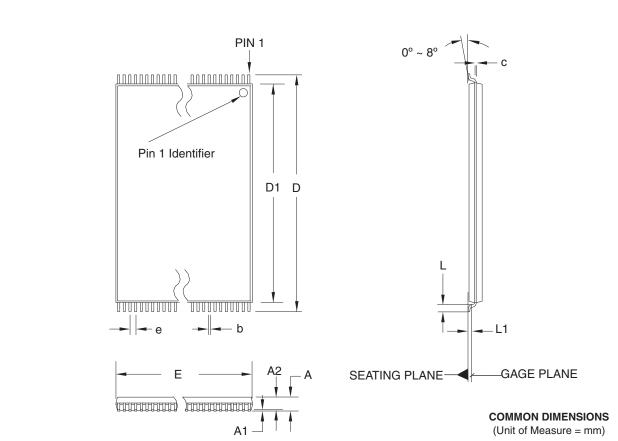
TITLE	
32J , 32-lead,	Plastic J-leaded Chip Carrier (PLCC)

DRAWING NO.	REV.
32J	В





27.2 32T - TSOP



Notes:

- 1. This package conforms to JEDEC reference MO-142, Variation BD.
- 2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
- 3. Lead coplanarity is 0.10 mm maximum.

SYMBOL	MIN	NOM	MAX	NOTE
Α	_	_	1.20	
A1	0.05	_	0.15	
A2	0.95	1.00	1.05	
D	19.80	20.00	20.20	
D1	18.30	18.40	18.50	Note 2
E	7.90	8.00	8.10	Note 2
L	0.50	0.60	0.70	
L1	0.25 BASIC			
b	0.17	0.22	0.27	
С	0.10	_	0.21	
е	0.50 BASIC			

10/18/01

	_	TITLE	DRAWING NO.	REV.
AIME	2325 Orchard Parkway San Jose, CA 95131	32T , 32-lead (8 x 20 mm Package) Plastic Thin Small Outline Package, Type I (TSOP)	32T	В

Revision History

Doc. Rev.	Date	Comments
03531	08/2009	Updated AC Charcteristisitics and ordering information.
03531	07/2009	Add a revision history page and update this version 'I' with the changes (AC charactertistics and ordering info from the word file).





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TC58NVG0S3HBAI4 5962-8751413XA TC58BVG0S3HBAI4 TH58NYG3S0HBAI6 CAT25320YIGT-KK CAT25320DWF LE24C162-RE 5962-8751417YA 5962-8751409YA CAT25M01LI-G DS28E11P+ BR9016AF-WE2 LE2464DXATBG CAS93C66VP2I-GT3
DS28E25+T DS28EL15Q+T M95320-DFDW6TP DS28E05GB+T AT25320B-SSPDGV-T HE24C64WLCSPD BL24SA128B-CSRC
24FC16T-I/OT 24FC08T-I/OT M24128-BFMN6TP S-24CS04AFM-TFH-U M24C04-FMC5TG M24C16-DRMN3TPK M24C64-DFMN6TP
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